

Attachment No. 2

CE-2.9 SUBCOMMITTEE ON SOCKETS

20 April, 2004, Tampa, FL

Harvey Waltersdorf welcomed everyone, and said that the meeting would be conducted following the published agenda.

1. The minutes of the October 8, 2003 meeting in San Antonio were approved.
2. Reaffirmed Documents

A. SP-4970: EIA-540DAAA-A: Detail, DIP

It was noted in the minutes of the last meeting that this standard had received insufficient votes.

The document will be sent out on a second 30-day SP ballot. If there are sufficient votes (at this committee meeting and SP ballot) for approval received, with no negative comments, it was moved and approved to send to EIA for EDEC ballot. The following members present approved this ballot/action: Harvey Waltersdorf, Bob Druckenmiller, Arun Shah, Frank Ruffino, John Healey, Rick Zulkiewicz.

B. SP-4971: EIA-700A0AB: 68-pin Memory Card Connector (Ballot expired 8/27/01. Due to insufficient responses, reballoted with expiration 3/25/02)

It was noted in the minutes of the last meeting that this standard had received insufficient votes.

The document will be sent out on a second 30-day SP ballot. If there are sufficient votes (at this committee meeting and SP ballot) for approval received, with no negative comments, it was moved and approved to send to EIA for EDEC ballot. The following members present approved this ballot/action: Harvey Waltersdorf, Bob Druckenmiller, Arun Shah, Frank Ruffino, John Healey, Rick Zulkiewicz.

3. Pink Sheet Ballots

A. SP-3874: Detail, SODIMM (Tyco is sponsor. New draft needed!)

B. SP-4965: Rev. EIA-540B0AE: Detail Land Grid Array (Contech Research is sponsor. Update being prepared.)

It was suggested by the committee that this document is really a test sequence and should be addressed by CE-2.1.

C. SP-4972: EIA-540B0AD: Low Pin Count LGA (It was moved and approved to cancel this document and incorporate information into SP-4965.)

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D. SP-4973: EIA-540B0AB: Low Pin Count BGA (Ballot expired 4/11/02)

It was suggested by the committee that this document is really a test sequence and should be addressed by CE-2.1.

E. SP-4982: EIA-5400000A: Generic

It was moved and approved to send to EIA for a second SP ballot due to insufficient votes at the last ballot.

F. SP-4983: EIA-540BAAA-A: Detail, Mechanically Actuated PGA (Contech Research is the sponsor)

Awaiting a revised document

4. Draft Documents

A. PN-4114: Rev. EIA-540FA00, (Streamlined) Blank, Multi-Package Modules (Molex is sponsor)

It was moved and approved to cancel the project.

B. PN-5055 Replacement document for EIA-676 Detail, SFF 1.8" (15 mm) Disk Drives
Harvey handed out a copy of the rewritten draft. Carl will format and send to Harvey for ballot. It was moved and approved to send the document to EIA for SP ballot. Harvey will provide EIA with a list of SFF Committee members to receive the ballot as well.

5. Five Year Review

A. EIA-540C000: Sectional Relay Sockets (John Bruno of Deutsch is reviewing)

Awaiting response from Deutsch on whether to rescind, reaffirm or revise.

B. EIA-540CA00: Blank, Relay Sockets (John Bruno of Deutsch is reviewing)

Awaiting response from Deutsch on whether to rescind, reaffirm or revise.

C. EIA-540CAAA: Detail, 10A Relay Socket (John Bruno of Deutsch is reviewing)

Awaiting response from Deutsch on whether to rescind, reaffirm or revise.

D. EIA-540CAAB: Detail, 5A Relay Socket (John Bruno of Deutsch is reviewing)

Awaiting response from Deutsch on whether to rescind, reaffirm or revise.

E. It was moved and approved to send out the following documents for reaffirmation:

- EIA-700A0AC: Detail, 88-pin DRAM Connector
- EIA-540A000-A: Sectional, Chip Carrier Sockets
- EIA-540AA00: Blank, Leadless Chip Carrier Sockets
- EIA-540AAAA: Detail, Type A Chip Carrier Sockets
- EIA-540AB00: Blank, PQFP
- EIA-540ABAA: Detail, PQFP
- EIA-540AC00: Blank, PCC

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- EIA-540ACAA: Detail, PCC
- EIA-540AD00: Blank, Adaptor QFP to PGA
- EIA-540B000: Sectional, PGA
- EIA-540BA00: Blank, PGA
- EIA-540BAAB: Detail, Non-Mechanical PGA
- EIA-540BAAC: Detail, Flex Carrier PGA
- EIA-540D000-A: Sectional, In-Line Packages
- EIA-540DA00: Blank, DIP (Will be sent out for review)
- EIA-540DAAB: Detail, Flex Carrier DIP
- EIA-540EA00: Blank, Round Sockets
- EIA-540EAAA: Detail, Round Sockets
- EIA-540F000: Sectional, Multi-Package Modules

F. EIA-720: Detail, SFF 2.5” Disk Drives

Harvey showed a copy of the rewritten draft. Carl will format and send to Harvey for ballot. It was moved and approved to send the document to EIA for SP ballot. Harvey will provide EIA with a list of SFF Committee members to receive the ballot as well.

G. • EIA-674: Detail, SFF 1.8” Disk Drives

The SFF rewritten draft has the wrong EIA document number on it. Harvey showed a copy of the rewritten draft. Carl will format and send to Harvey for ballot. It was moved and approved to send the document to EIA for SP ballot. Harvey will provide EIA with a list of SFF Committee members to receive the ballot as well.

H. EIA-675: Detail, SFF 1.3” Disk Drives

It moved and approved to rescind this document.

I. EIA-677: Detail, SFF Power Connector Pin Dimensions

It was moved and approved to send out for reaffirmation.

7. New Business

Harvey presented a draft of a detail specification for Two-Piece, Low Insertion Force, High Speed, Stacking Array Connector for Use in Electronic Equipment.

All actions taken by the subcommittee were moved and unanimously approved by the EIA CE-2.0 committee. The meeting adjourned at 11:45 AM on 20 April 2004.

Respectively

Harvey Waltersdorf
Chairman